### **Composite Transistors**

# XN0F261 Silicon NPN epitaxial planar type

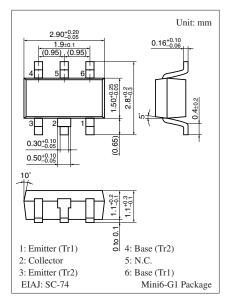
#### For muting

#### Features

- Two elements incorporated into one package (Collector-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

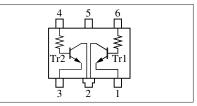
Absolute Maximum hatings $T_a = 23$ C							
Parameter	Symbol	Rating	Unit				
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	30	V				
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V				
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V				
Collector current	I <sub>C</sub>	600	mA				
Total power dissipation	P <sub>T</sub>	300	mW				
Junction temperature	Tj	150	°C				
Storage temperature	T <sub>stg</sub>	-55 to +150	°C				

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$



#### Marking Symbol: 6B

#### Internal Connection

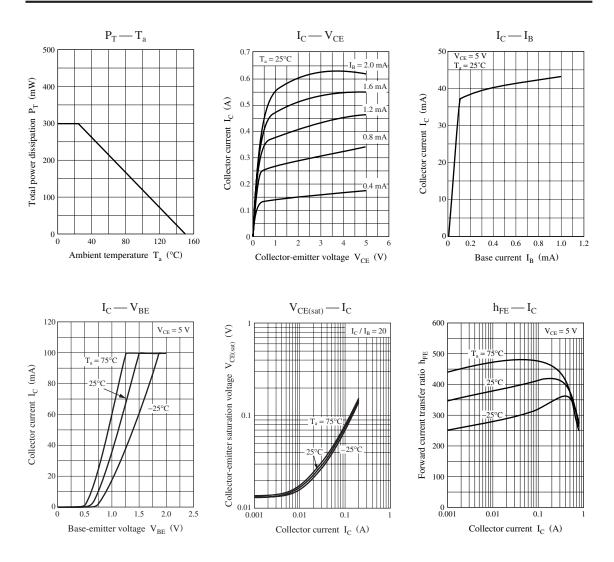


Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{C} = 1 \ \mu A, I_{E} = 0$	30			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{C} = 1 \text{ mA}, I_{B} = 0$	20			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_E = 1 \ \mu A, \ I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 30 V, I_E = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 5 V, I_C = 0$			1	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 5 \text{ V}, I_C = 50 \text{ mA}$	100		600	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = 50 \text{ mA}, I_{\rm B} = 2.5 \text{ mA}$			80	mV
Input resistance	R <sub>1</sub>		-30%	3.3	+30%	kΩ
Transition frequency	f <sub>T</sub>	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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